## **EAST Search History**

| Ref<br># | Hits     | Search Query  | DBs   | Default<br>Operator | Plurals | Time Stamp       |
|----------|----------|---|---|---------------------|---------|------------------|
| L6       |          | (circuit IC die chip) near (lid cover) with (project\$3 protrud\$3) with engag\$3   | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR                  | ON      | 2007/09/10 08:42 |
| L7       | 3        | ("4580157"   "4975762"   "5268533").PN.   | US-PGPUB;<br>USPAT;<br>USOCR  | OR                  | ON      | 2007/09/10 08:41 |
| L8       | 0        | ("6611054").URPN.   | USPAT   | OR                  | ON      | 2007/09/10 08:41 |
| L9       | 1035     | attach\$4 and detach\$4 and (circuit IC die chip) near (lid cover)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR .                | ON      | 2007/09/10 08:44 |
| L10      | 25017133 | @ad<"20031007"  | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR                  | ON      | 2007/09/10 10:38 |
| L11      | 552      | L9 and L10  | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR                  | ON      | 2007/09/10 08:45 |
| L12      | 1500     | 257/704.ccls.   | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR                  | ON      | 2007/09/10 09:08 |
| L13      | 1231     | L12 and L10   | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR                  | ON      | 2007/09/10 10:14 |
| L14      | 11       | ("20010008776"   "20020175421"   "20020195270"   "5424573"   "5616957"   "5977626"   "6414385"   "6437984"   "6608763"   "6703698"   "6734552").PN. | US-PGPUB;<br>USPAT;<br>USOCR  | OR                  | ON      | 2007/09/10 09:18 |

## **EAST Search History**

|     |       |   |   |    | <sub>I</sub> |                  |
|-----|-------|---|---|----|--------------|------------------|
| L15 | 2     | ("5583373"   "5610431").PN.   | US-PGPUB;<br>USPAT;<br>USOCR  | OR | ON           | 2007/09/10 09:28 |
| L16 | 8     | ("4417392"   "4901136"   "4954878"  <br>"5012323"   "5095359"   "5220195"  <br>"5223741"   "5237204").PN. | US-PGPUB;<br>USPAT;<br>USOCR  | OR | ON           | 2007/09/10 09:29 |
| LI7 | 3308  | (lid cover) with attach\$4 with detach\$4 with (device chip die IC circuit)                               | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR | ON           | 2007/09/10 10:19 |
| L18 | 2170  | L17 and L10   | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR | ON           | 2007/09/10 10:16 |
| L19 | 139   | 18 and substrate  | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR | ON           | 2007/09/10 10:16 |
| L20 | 139   | (lid cover) with attach\$4 with detach\$4 with (device chip die IC circuit) near (substrate board wafer)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR | ON           | 2007/09/10 10:39 |
| L21 | 95    | (lid cover) with attach\$4 near detach\$4 with (device chip die IC circuit) near (substrate board wafer)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR | ON           | 2007/09/10 10:38 |
| L22 | 33608 | (lid cover) with (device chip die IC circuit) near (substrate board wafer)                                | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR | ON           | 2007/09/10 10:38 |
| L23 | 24330 | 22 and @ad<"20031007"   | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR | ON           | 2007/09/10 10:38 |

## **EAST Search History**

| L24 | 844 | 23 and attach\$4 with detach\$4 | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR | ON   | 2007/09/10 10:40 |
|-----|-----|---------------------------------|---|----|------|------------------|
| L25 | 0   | 24 and semocnductor             | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR | ON . | 2007/09/10 10:47 |
| L26 | 192 | 24 and semiconductor            | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR | ON   | 2007/09/10 10:47 |
| L27 | 215 | 24 and packag\$3                | US-PGPUB;<br>USPAT;<br>USOCR;<br>FPRS; EPO;<br>JPO;<br>DERWENT<br>; IBM_TDB | OR | ON   | 2007/09/10 10:51 |